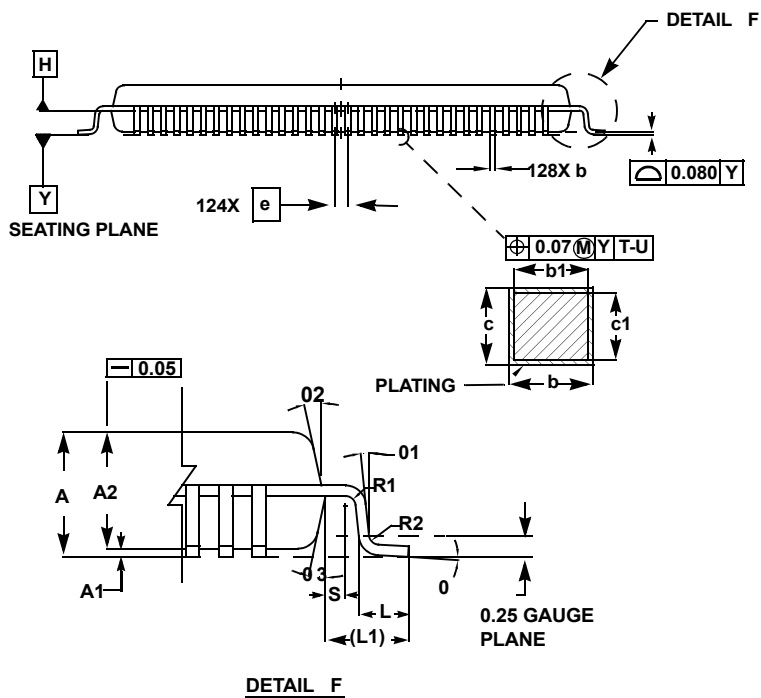
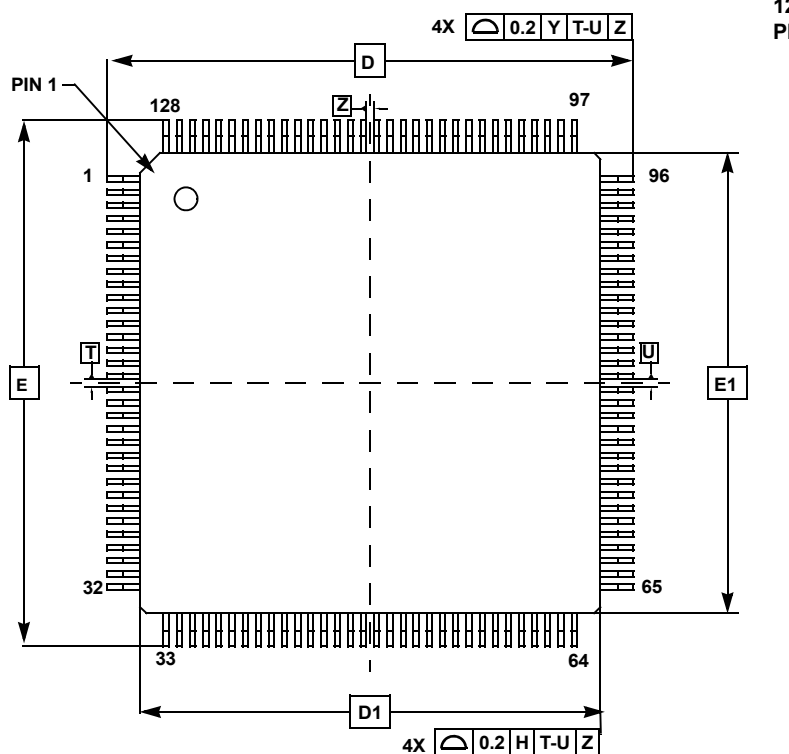


# Plastic Packages for Integrated Circuits

## Low Plastic Quad Flatpack Packages (LQFP)

### Q128.14x14

128 LEAD LOW PLASTIC QUAD FLATPACK PACKAGE .4 MM PITCH



SYMBOL	MILLIMETERS			NOTES
	MIN	NOM	MAX	
A	-		1.60	-
A1	0.05		0.15	-
A2	1.35	1.40	1.45	-
b	0.13	0.16	0.23	4
b1	0.13	-	0.19	-
c	0.09	-	0.20	-
c1	0.09	-	0.16	-
D	16 BSC			-
D1	14 BSC			3
E	16 BSC			-
E1	14 BSC			3
L	0.45	0.60	0.75	-
L1	1.00 REF			-
R1	0.08	-	-	-
R2	0.08	-	0.20	-
S	0.20	-	-	-
0	0°	3.5°	7°	-
01	0°	-	-	-
02	11°	12°	13°	-
03	11°	12°	13°	-
N	128			-
e	0.40 BSC			-

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#### NOTES:

- Dimensions are in millimeters. Dimensions in ( ) for Reference Only.
- Dimensions and tolerances per AMSEY14.5M-1994.
- Dimensions D1 and E1 are excluding mold protrusion. Allowable protrusion is 0.25 per side. Dimensions D1 and E1 are exclusive of mold mismatch and determined by datum plane H.
- Dimension b does not include dambar protrusion. Allowable dambar protrusion shall not cause the lead width to exceed the maximum b dimension by more than 0.08mm. Dambar cannot be located at the lower radius or the foot. Minimum space between protrusion and an adjacent lead is 0.07 mm.